Future (heterogeneous) system integration especially when fast switching SiC or GaN power devices are involved:

- alleviate problems related to fast switching on the module or SIP level
- reduce number of production steps (cost savings)
- high production volume required to justify initial costs
- select the partitioning and interfaces intelligently!

Which partitioning makes sense:

- **Switching Cell in Package**
  - this critical part of the circuit is encapsulated in the package

- **Power System in Package**
  - integration of full functions including passives
  - Examples: PFC, DC/DC converter, half bridge including output inductor

ECPE Lighthouse Programme:

**msPEBB**: modular and scalable Power Electronics Building Block